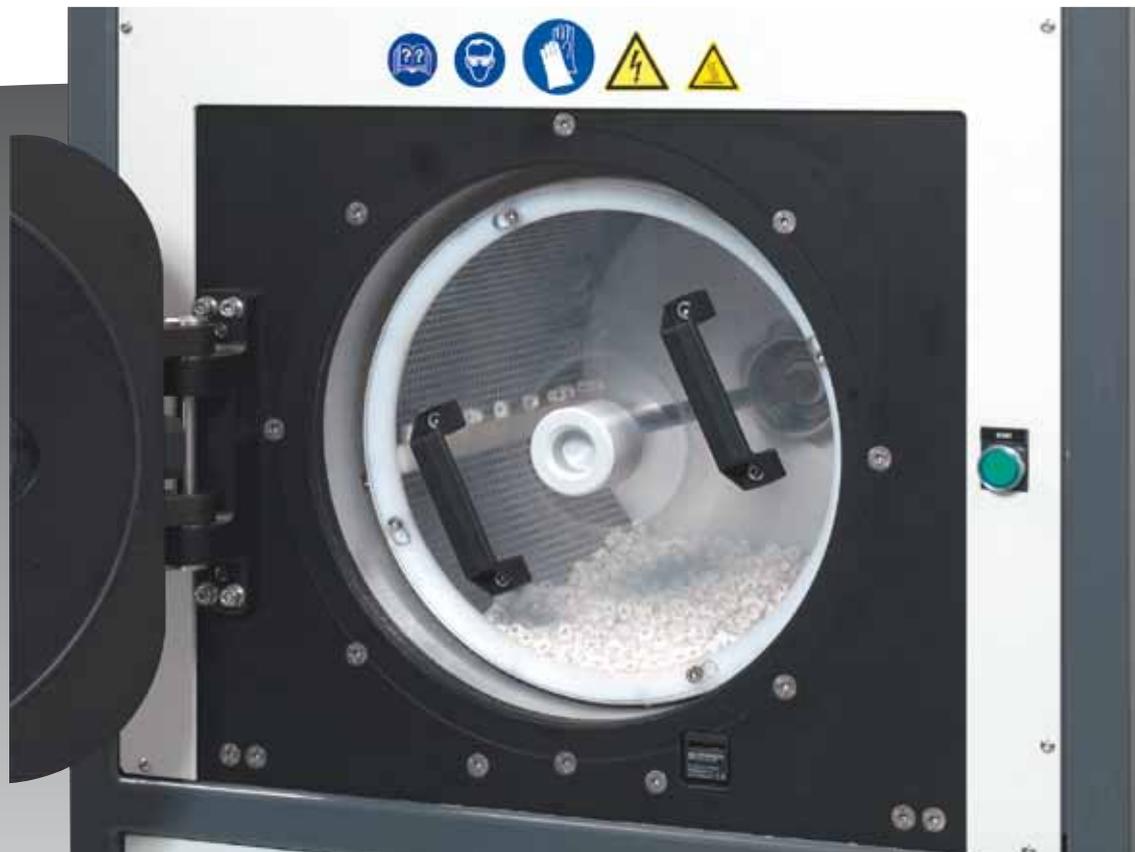


Product Information

RotoVAC - Vacuum Plasma Treater



RotoVAC - Vacuum Plasma Treater

Standard and Customised Vacuum Plasma Treaters

Tantec RotoVAC plasma treater is designed for plasma treatment of small injection moulded plastic parts, without the need to place them in a jig or use complicated handling systems. With the RotoVAC drum design, simply fill the drum and place it in the vacuum chamber. The rotation will ensure that all parts are treated.

In the treating chamber a vacuum builds up to between 1 and 4 mbar before an electrical discharge is created through the integrated plasma electrode. Treatment cycle times are often short, between 20-180 seconds depending on the material and its formulation.

The RotoVAC plasma treater is appreciated for its simplicity of operation, reliability in production and fast process speed. Treating gasses such as argon and oxygen can be applied, but in most cases

this is not necessary due to the high power exposed by the plasma discharge.

RotoVAC uses the advanced Tantec power generator HV-X series as power supply, and specially designed plasma transformers to provide voltage to the plasma electrodes. The rotating drum ensures that all parts are equally treated. The concept includes an extra drum which can be loaded during treatment and simply exchanged with the one in use when the batch is completed.

TECHNICAL DATA

Features:

- ▶ Easy to install and use
- ▶ Fast treatment times
- ▶ Standard or customised chambers
- ▶ Vacuum level
- ▶ Process gas
- ▶ Process control
- ▶ Cost efficient surface treatment
- ▶ Vacuum pressure plasma

TechnicalData

Plasma & Corona Treaters

gluing bonding coating
adhesion adhesion
coating bonding
gluing bonding coating

Features:

Easy to install and use

Connect to mains power and compressed air.

Fast treatment times

High power impact enables treatment times from 20-180 seconds, depending on material.

Standard or customised chambers

Chamber and drum size can be designed to most applications. Many available as standard.

Vacuum level

The plasma discharge is active from 1-4 mbar depending on application.

Process gas

Process gasses such as oxygen and argon can be used, but in most cases it is not necessary.

Process control

The entire plasma process is controlled by the HV-X generator and PLC unit. All parameters are displayed through the touch panel. (Standard – Proface).

Cost efficient surface treatment

Due to the low power and no need of special treatment gasses the unit is a very cost efficient solution for improving surface wettability and adhesion.

Vacuum pressure plasma

Enables treatment of both conductive and non-conductive surfaces.

Technical Specifications	RotoVAC Vacuum Plasma Treater
Mains voltage and frequency	230 VAC or 480 VAC 3Ph.
Output voltage/plasma power	Max. 400 Vp/max. 2000 Watt
Power supply	HV-X plasma generator series
Compressed air inlet	5-6 bar dry and clean
Process gas	Standard: air, oxygen, argon, nitrogen on request
Vacuum pump capacity in m ³ /min.	15 to 240 m ³ /min., depending on size of vacuum chamber
Vacuum level	1-4 mbar
Evacuation time, typical	15-60 seconds, depending on chamber size and pump capacity
Plasma treatment time, typical	20-180 seconds, depending on material
Control and connectivity	Complete with touch panel. (Standard - Proface)
Regulation compliance	CE - RoHS - WEEE

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